

DARPA MEMS Program and Application in Space

William C. Tang, Ph.D.
Program Manager,
MEMS / MPG / NMASP / CSAC
Microsystems Technology Office
Defense Advanced Research Projects Agency

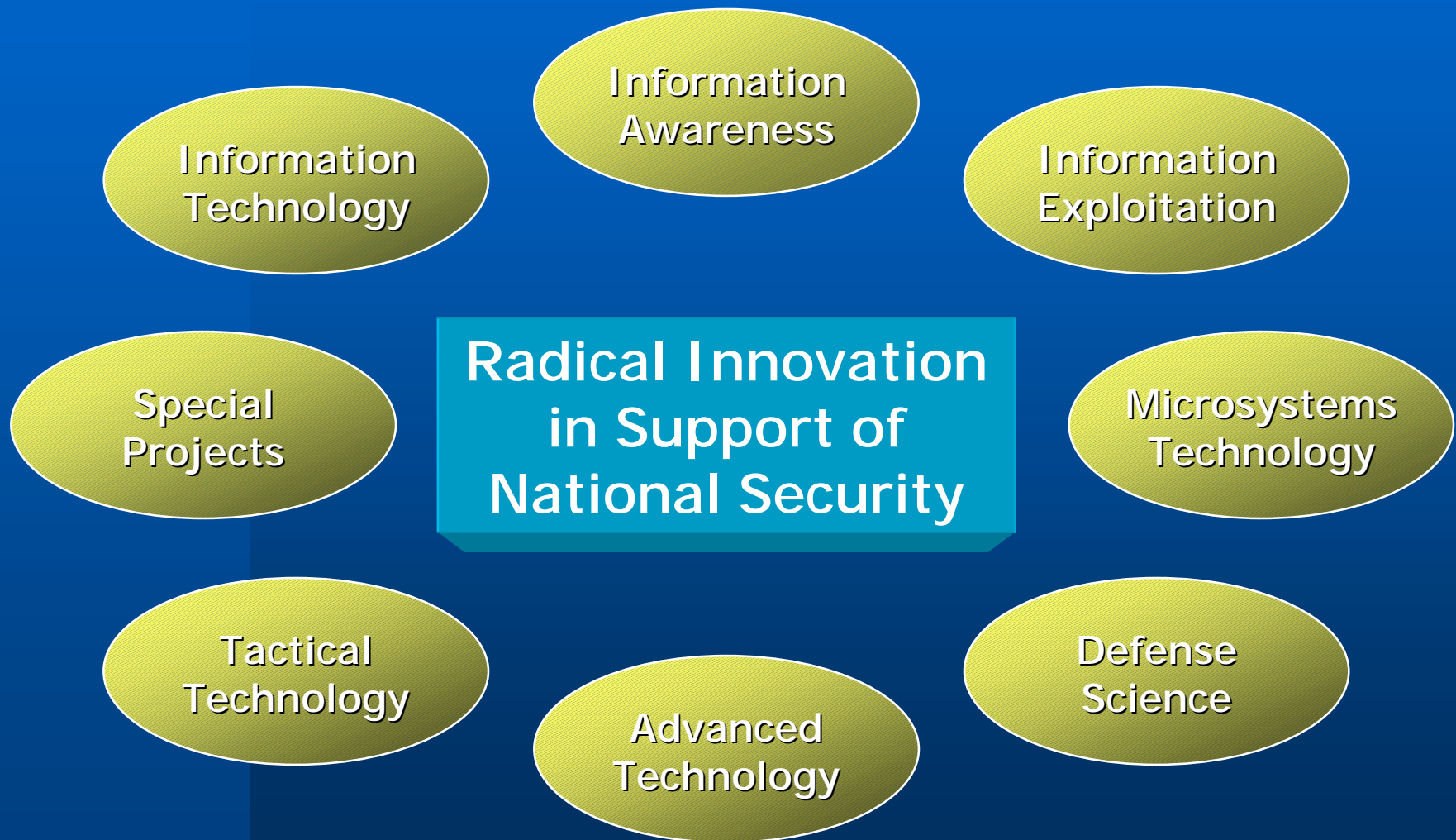


Outline

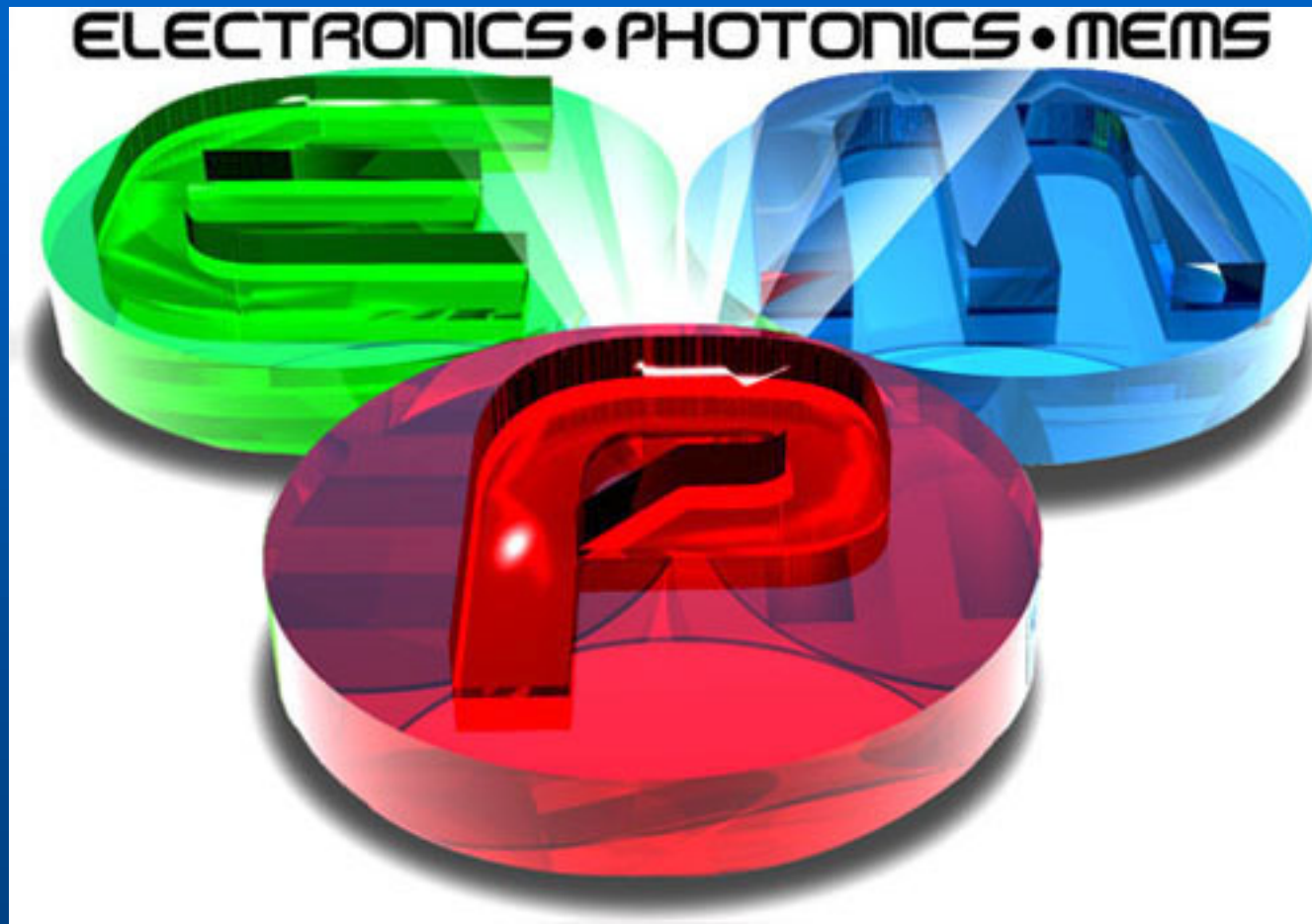


- Introduction
- Current Thrusts
- MEMS Applications in Space
- Conclusion

DARPA Mission



Microsystems Technology Office

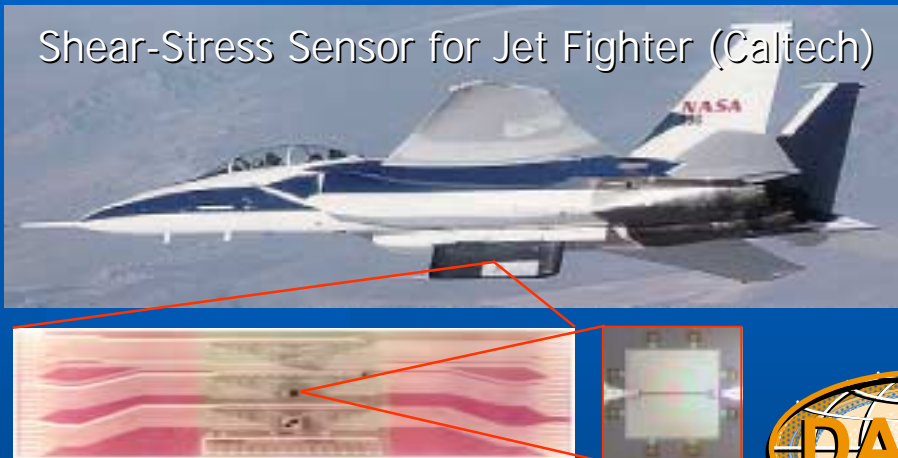


Technology for Chip-Level Integration of E. P. M.

MEMS Application Domains



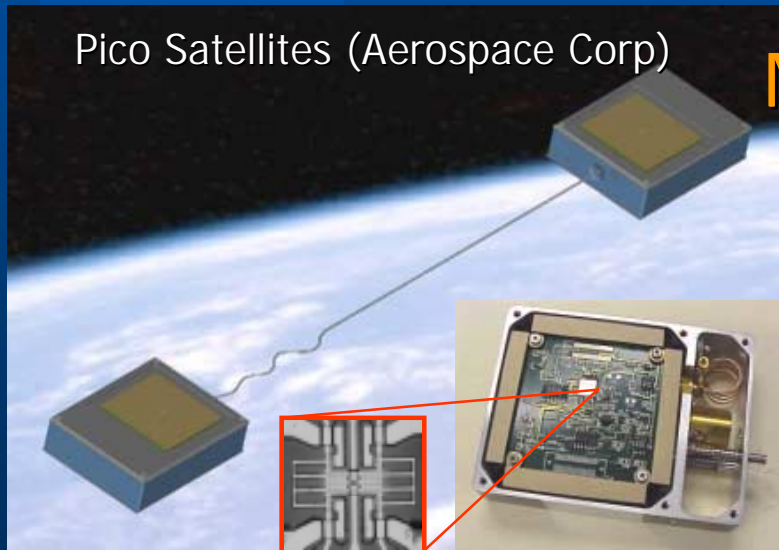
Shear-Stress Sensor for Jet Fighter (Caltech)



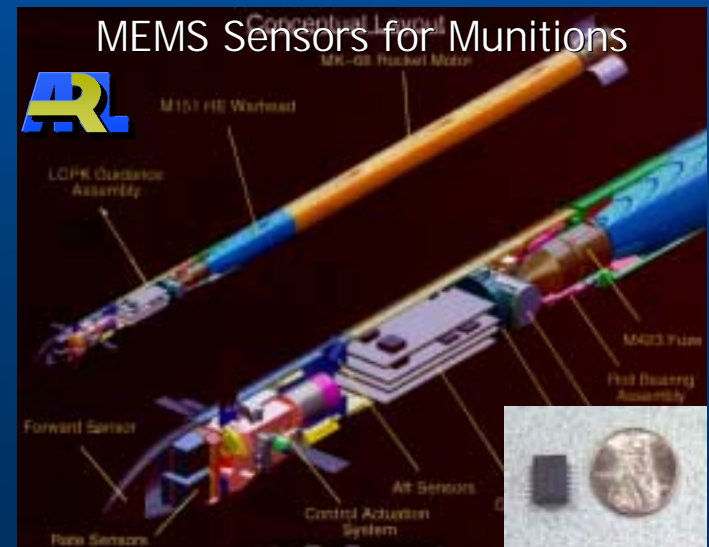
MEMS Exploder for Torpedoes



Pico Satellites (Aerospace Corp)



MEMS Sensors for Munitions



Pico Satellite Potential Applications



- Cooperative constellations
- Sparse aperture antennas
- Inspect and service missions
- Extremely agile launch-on-demand, short-term, survivable and robust communications and surveillance space systems

Picosat Current Technology



Batteries and Keepers



DC/DC Converter Board



Radio and Sensor Boards



Subcomponents

1. Patch Antenna Panel
2. Electronics Module with *Rockwell Science Center* Radio and MEMS Switches
3. Picosat Body
4. Tether Spool
5. Tether Coupler
6. 50Ω Splitter Board



Antenna Panel:
Front / Back



50Ω Splitter



Thermal Isolation Bracket

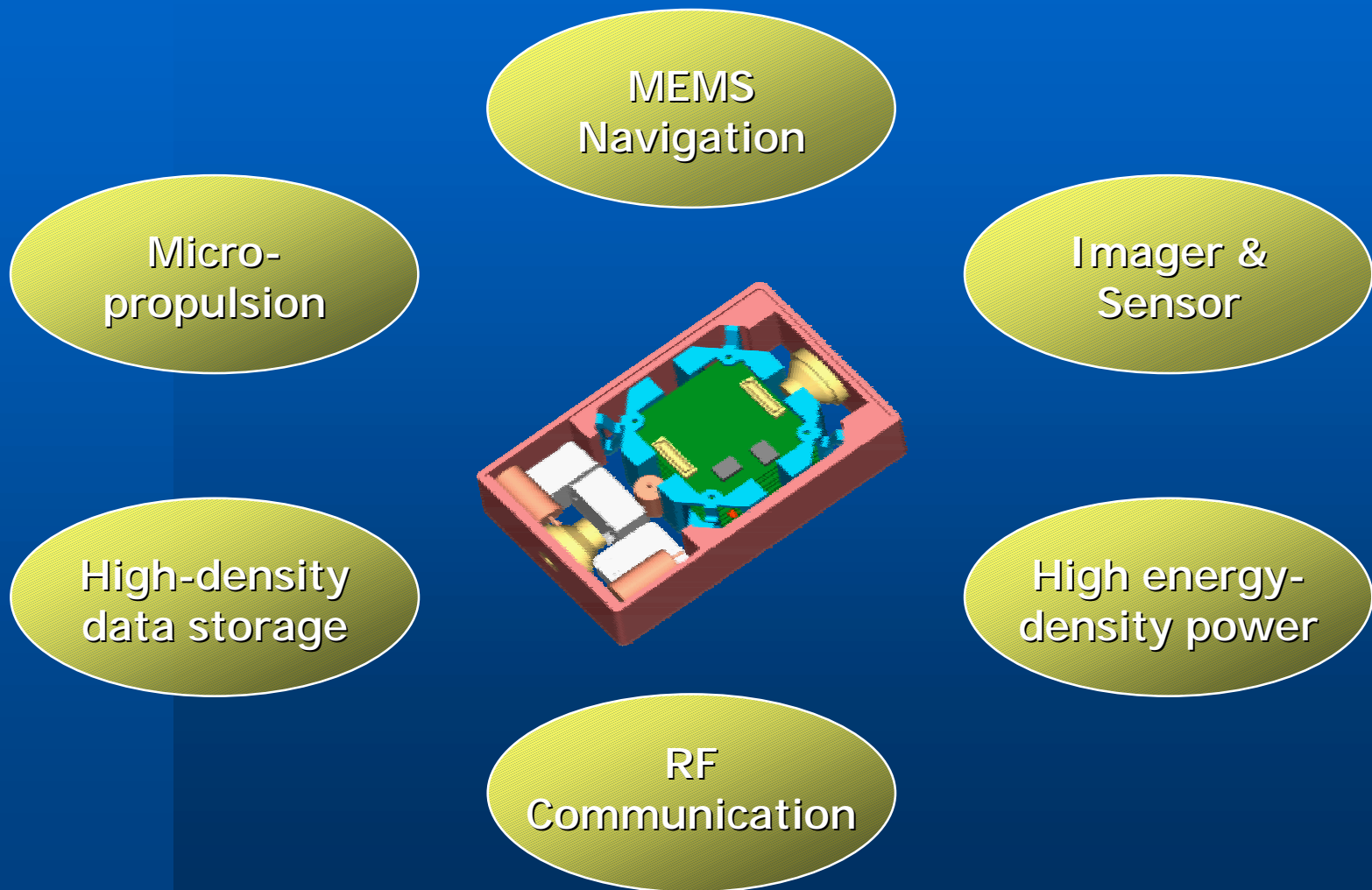


Tether Spool,
Flight Configuration

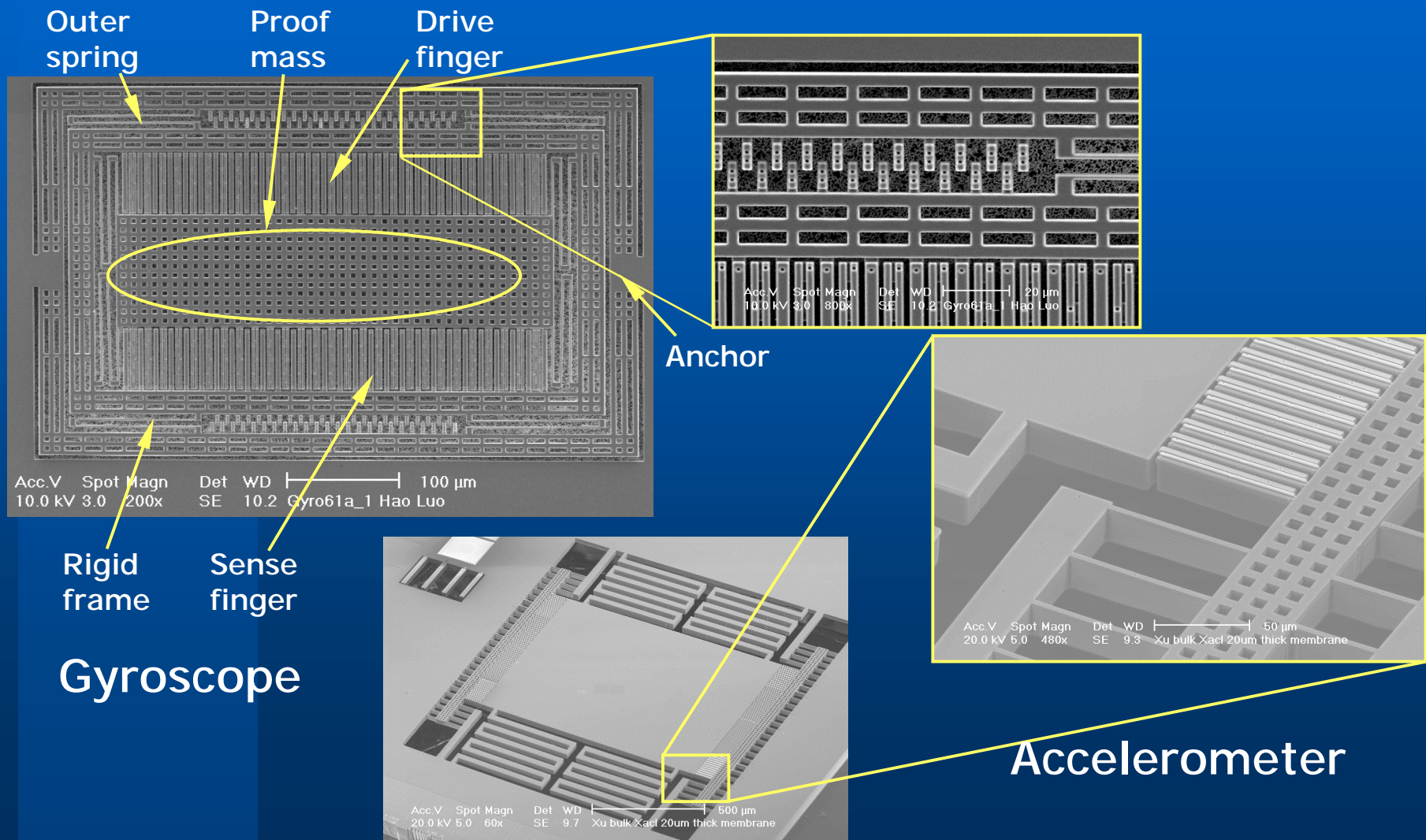


Tether Spool,
Testing

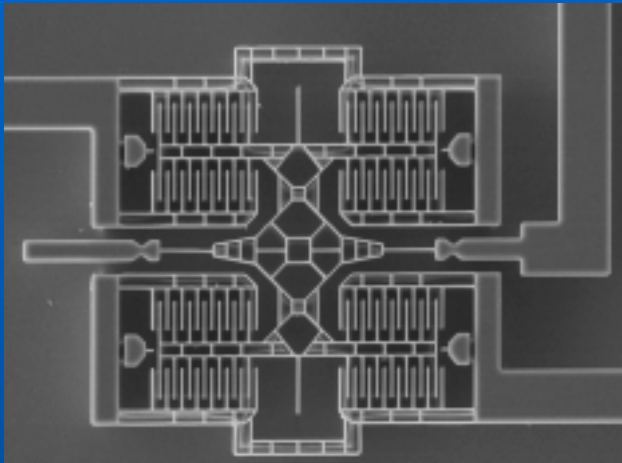
Potential MEMS Components for Future Picosat



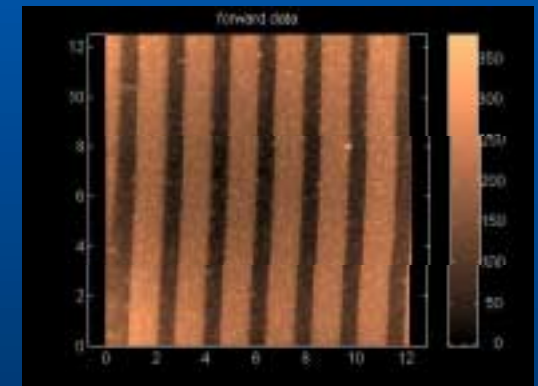
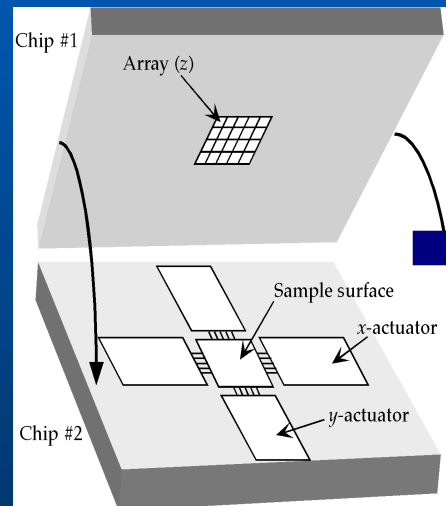
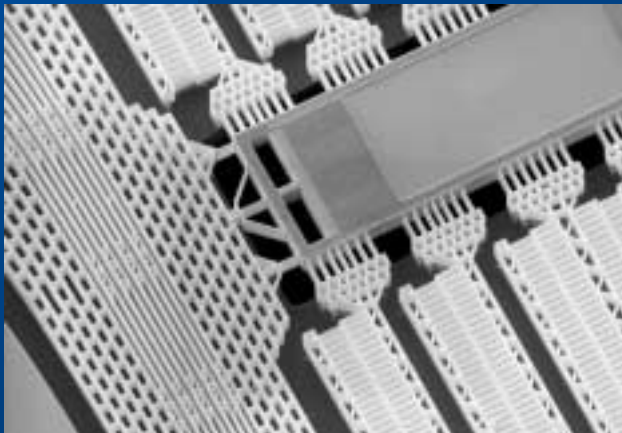
MEMS Inertial Sensors



MEMS Actuators for Data Storage



Parallel atomic force imaging with MEMS to exceed densities of conventional magnetic and optical storage



Areal density: 1-100 Gb/cm²
Transfer Rates: 0.1-10 Mb/s
Size: 0.5 cm³
Power consumption: <1W

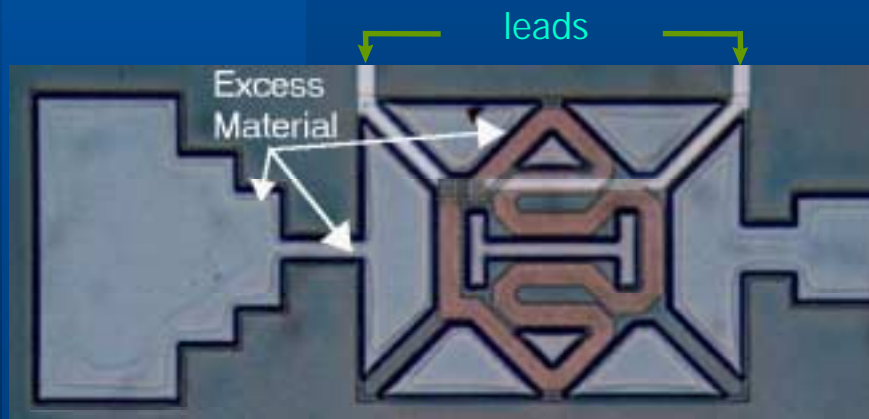


Micropropulsion

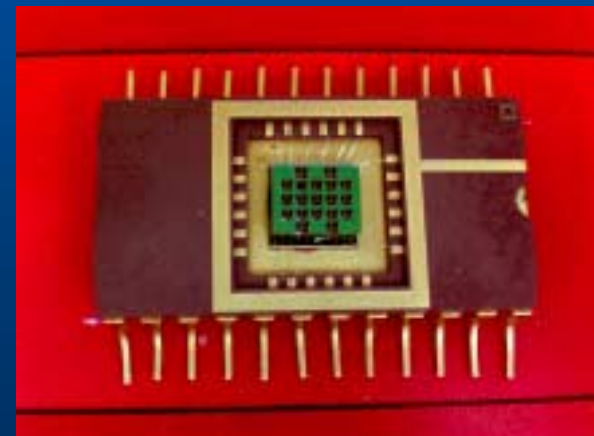
Cold gas thruster



2D nozzle in plastic



Microresistojet Thruster



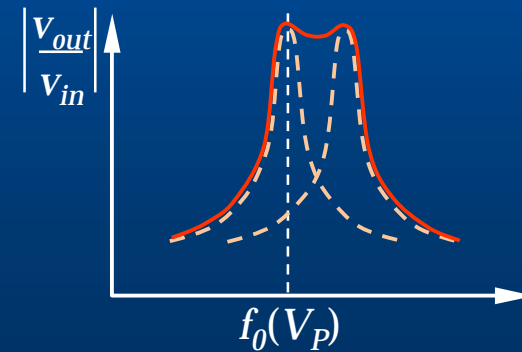
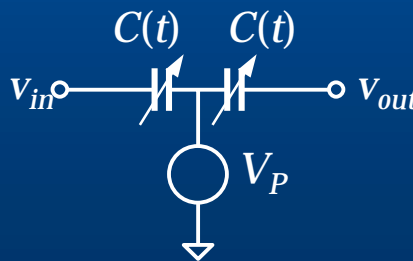
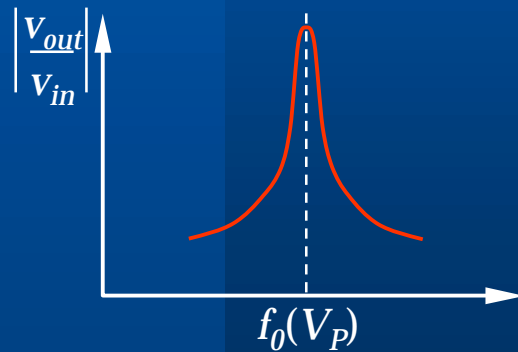
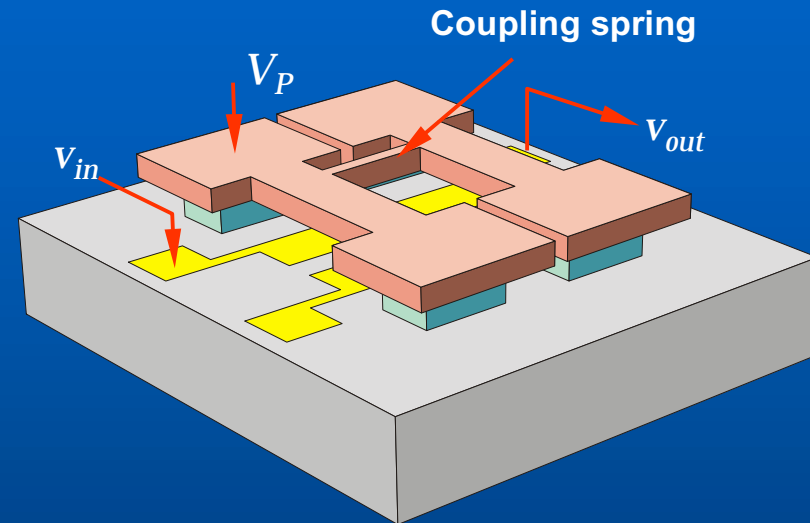
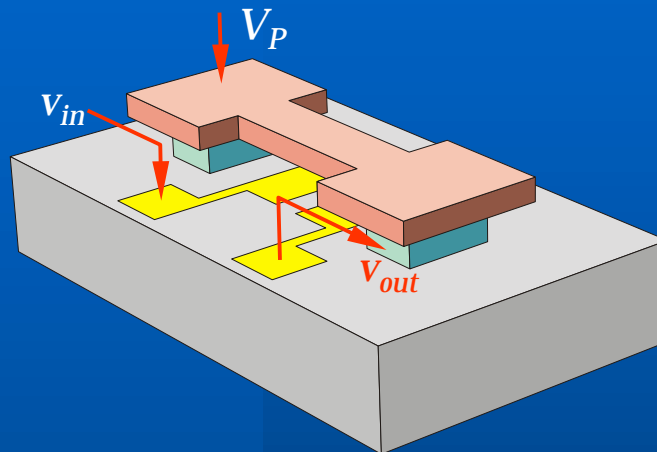
Digital Propulsion Chip

NMASP Program Goals

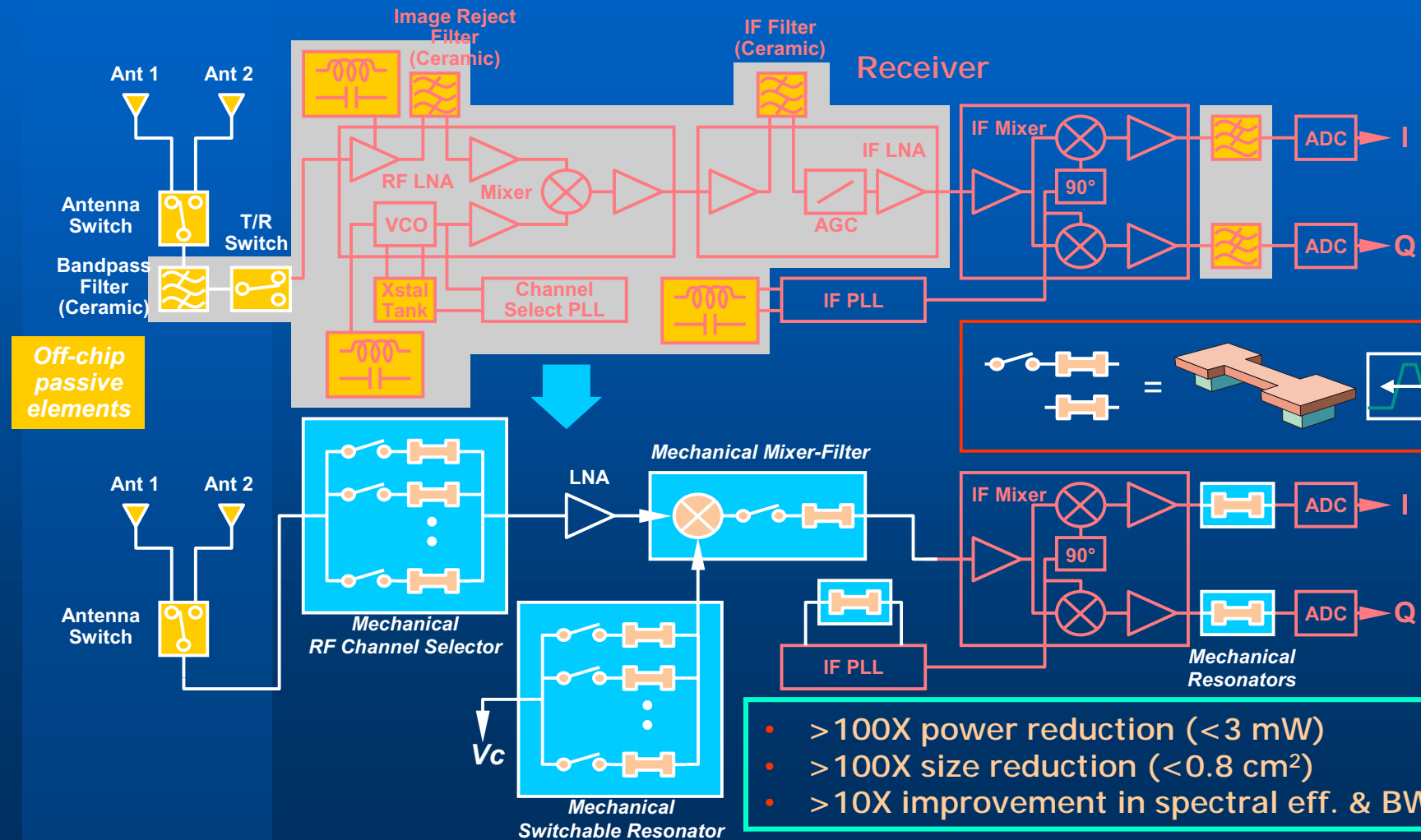


- Create arrays of precision, nano mechanical structures for RF-signal processing that will achieve
 - >100X reduction in size (80 cm² to 0.8 cm² or smaller)
 - >100X reduction in power consumption (300 mW to <3 mW)
 - >10X improvement in RF performance (spectral efficiency & bandwidth)
- Future Payoff
 - example: wristwatch-size UHF communicator/GPS receiver

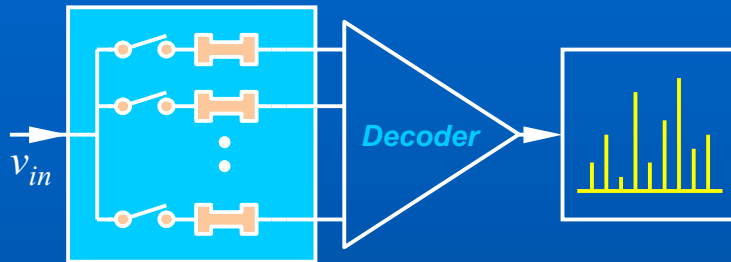
Mechanical Resonators as Filters



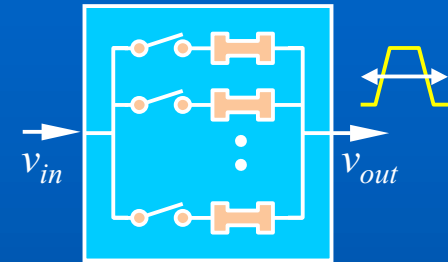
Mechanical Analog Signal Processing



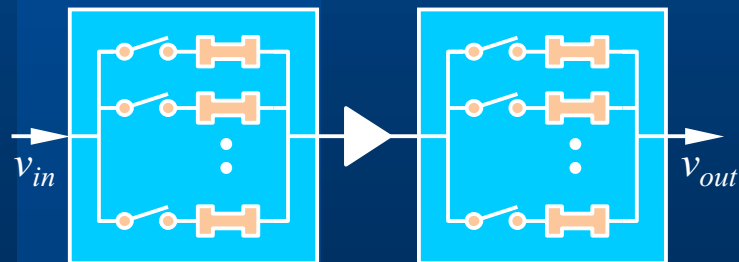
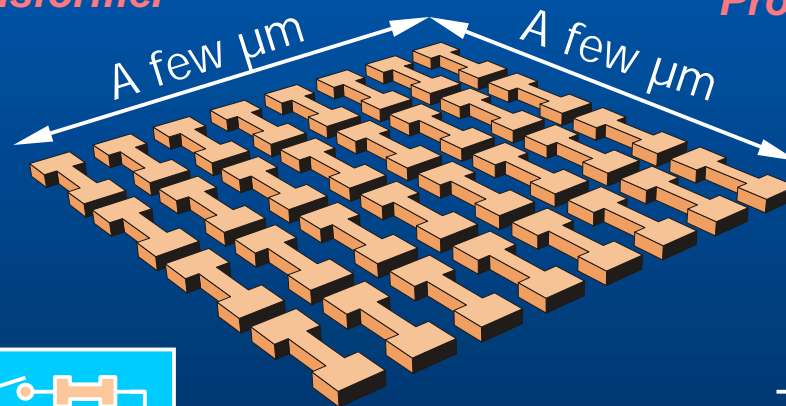
Signal Processing Possibilities



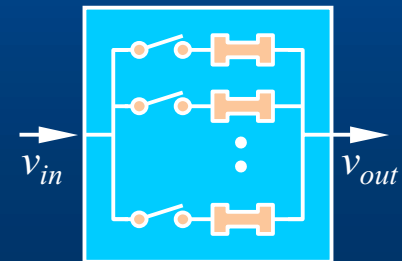
*Spectrum Analyzer /
Fourier Signal Transformer*



*Tracking Filter /
Discriminator /
Programmable Equalizer*



Frequency Converter



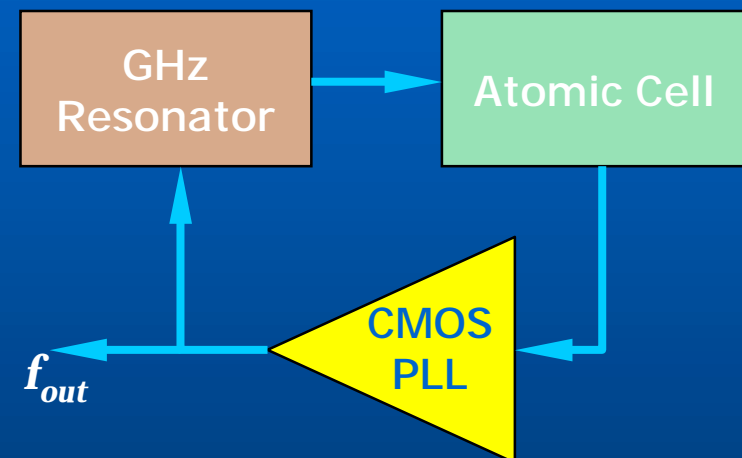
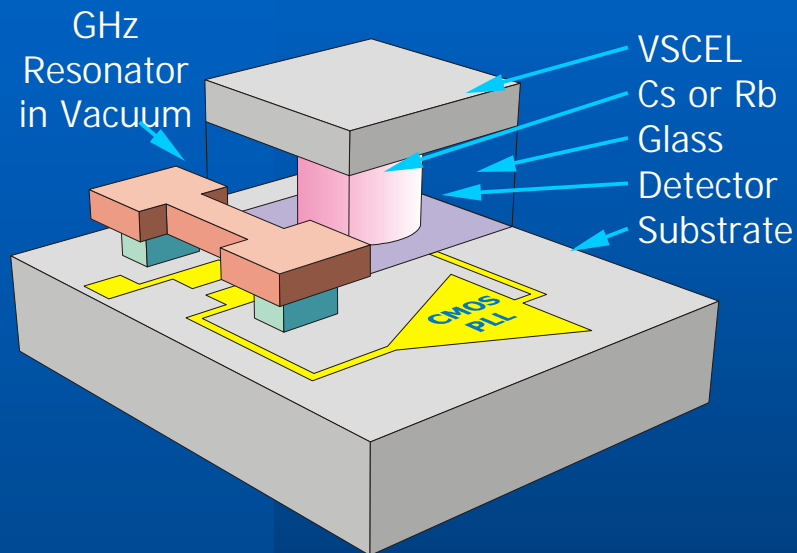
*Parametric Amplifier /
Digital Demodulator /
Envelope Detector*

Chip-Scale Atomic Clocks



- Create ultra-miniaturized, low-power, atomic time and frequency reference units that will achieve:
 - >200X reduction in size (from 230 cm³ to <1 cm³),
 - >300X reduction in power consumption (from 10 W to <30 mW), and
 - Matching performance ($\pm 1 \times 10^{-11}$ accuracy \Rightarrow <1 μ s/day).
- Examples of future payoffs:
 - Wristwatch-size high-security UHF communicator
 - Jam-resistant GPS receiver

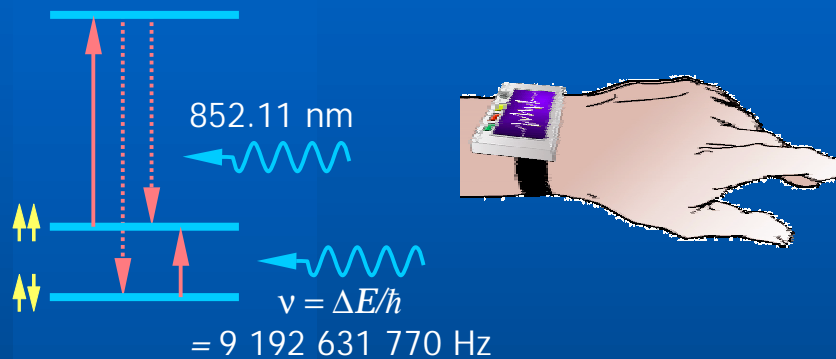
CSAC Miniaturization Concept



Phase locking GHz resonator with miniature atomic-confinement cell:

- Optical excitation \Rightarrow use VSCEL, eliminate μ -wave cavity (large & power-hungry)
- Optical detection \Rightarrow use photo-detector
- Mechanical resonator \Rightarrow electrostatic and capacitive coupling

Military Applications of CSAC



Ultra-miniaturized, low-power, atomic time and frequency reference units:

>200X reduction in size, >300X reduction in power & performance ($\pm 1 \times 10^{-11}$ accuracy \Rightarrow $< 1 \mu\text{s/day}$)



Clock accuracy of $1 \times 10^{-11} \Rightarrow$ 16-hour resynch interval or radio silence



9,000 commercial handheld GPS deployed in Desert Storm

Future of MEMS at DARPA



- Continue to establish new MEMS-enabled programs, both within MTO and in collaboration with other offices
- Continue to transition into DoD and commercial systems
 - Formation of the MEMS Industry Group